

MECHANICAL CASE OUTLINE

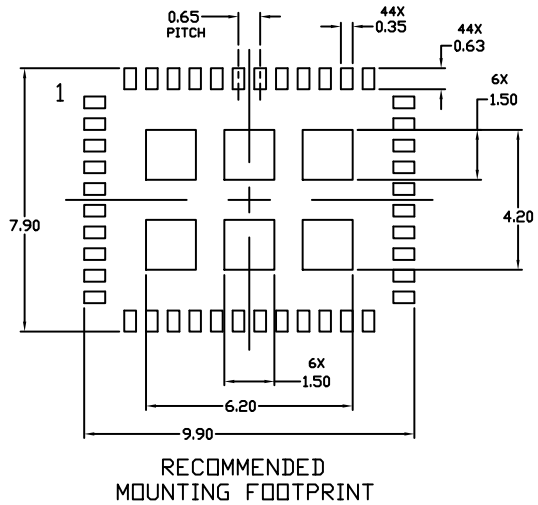
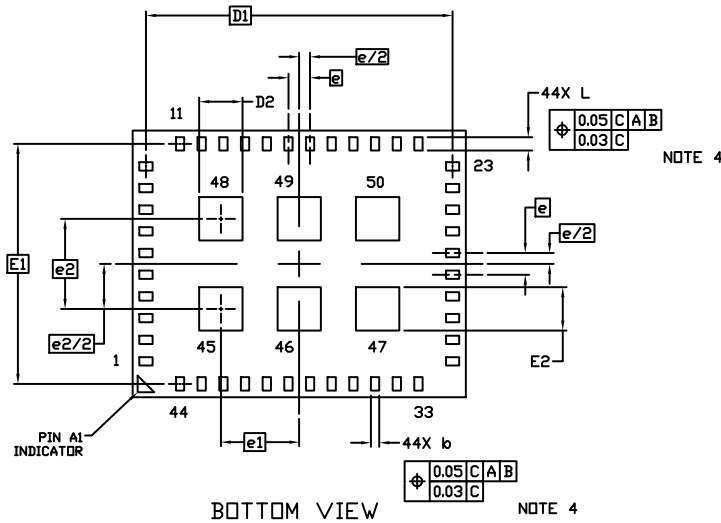
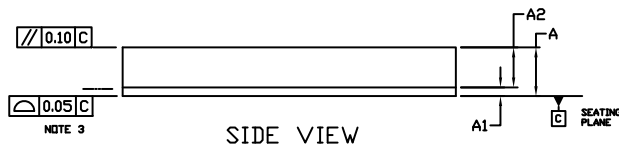
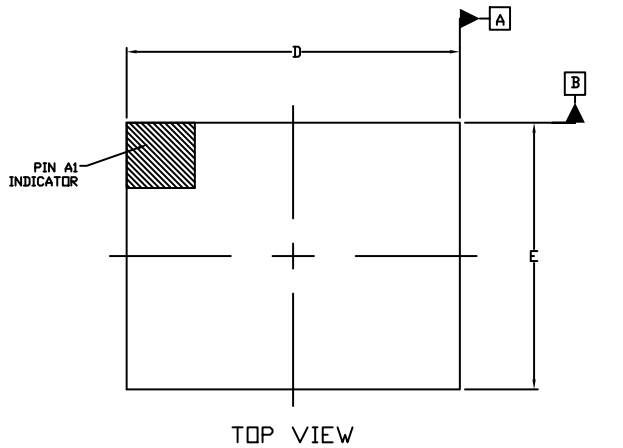
PACKAGE DIMENSIONS

ON Semiconductor®



SIP50, 10x8
CASE 127FD
ISSUE O

DATE 18 JAN 2019

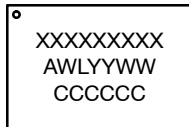


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.
3. POSITIONAL TOLERANCE APPLIES TO ALL OF THE PADS.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	1.40	1.46	1.52
A1	0.26 REF		
A2	1.16	1.20	1.24
b	0.20	0.25	0.30
D	9.90	10.00	10.10
D1	9.20 BSC		
D2	1.25	1.30	1.35
E	7.90	8.00	8.10
E1	7.20 BSC		
E2	1.25	1.30	1.35
e	0.65 BSC		
e1	2.35 BSC		
e2	2.70 BSC		
L	0.35	0.40	0.45

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- CCC = Country of Origin

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "μ", may or may not be present. Some products may not follow the Generic Marking.

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